

Applicant(s): Jong-hyon Ahn  
U.S. Serial No.: Not yet assigned

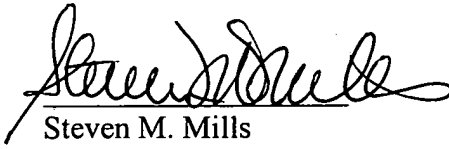
REMARKS

The amendments to the claims are made to clarify the description. No new matter is added to the application.

Attached hereto is a marked-up version of the changes made to the application by the current Amendment. The attached page is captioned "Version with Markings to Show Changes Made."

Respectfully submitted,

Date: June 12, 2001  
MILLS & ONELLO, LLP  
Eleven Beacon Street, Suite 605  
Boston, MA 02108  
Telephone: (617) 994-4900, Ext. 4901  
Facsimile: (617) 742-7774

  
Steven M. Mills  
Registration Number 36,610  
Attorney for Applicants

J:\SAM\0201\prelimamend.wpd

Applicant(s): Jong-hyon Ahn  
U.S. Serial No.: Not yet assigned

Version with Markings to Show Changes Made

In the Claims

Claim 10 has been amended as follows:

10. (Amended) A metal interconnect layer for a semiconductor device, comprising:  
a first upper portion having a first width;

a second middle portion having a second width, the second width being wider  
than the first width; and

a third lower portion having a third width, the third width being narrower [wider]  
than the [first and] second width[s].

05675556-001301